

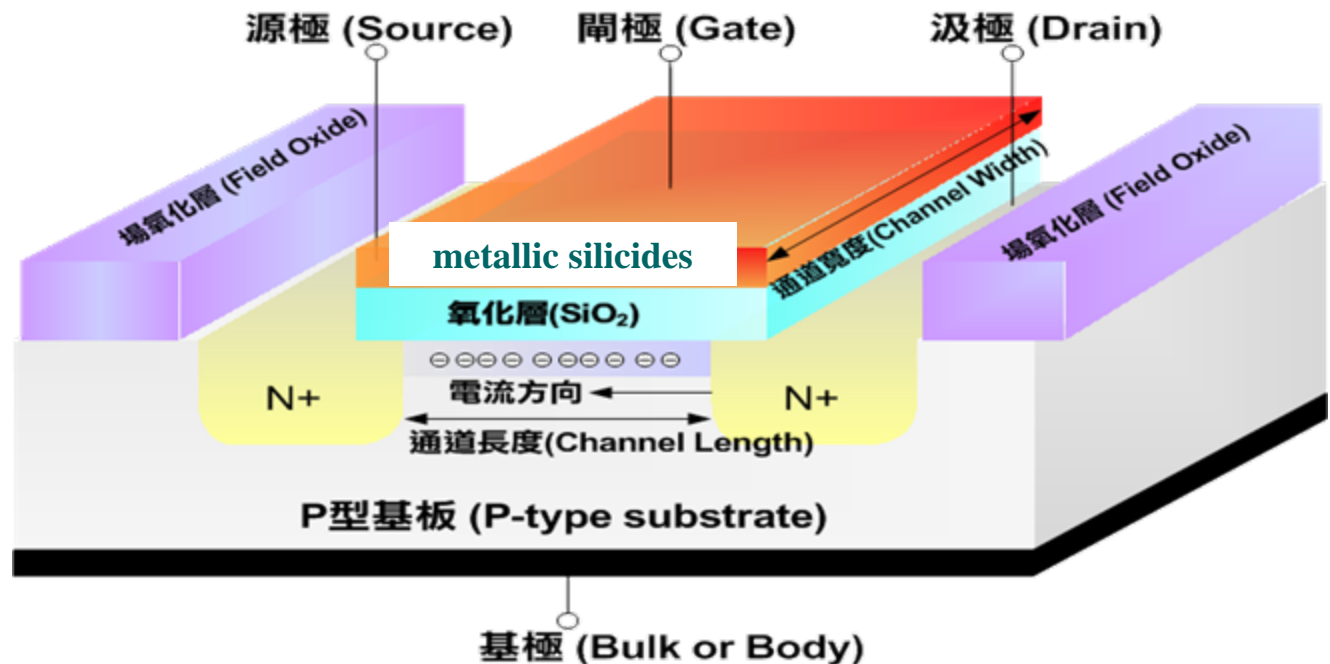


High temperature testing of TiSi_2 by Nanoindenter

二矽化鈦高溫奈米壓痕機性測試

Metallic silicides applied in semiconductor

- **High-temperature stability.**
- Schottky barriers and ohmic contacts.
- Low resistivity for gates and interconnects.
- Easy to etch for pattern generation.

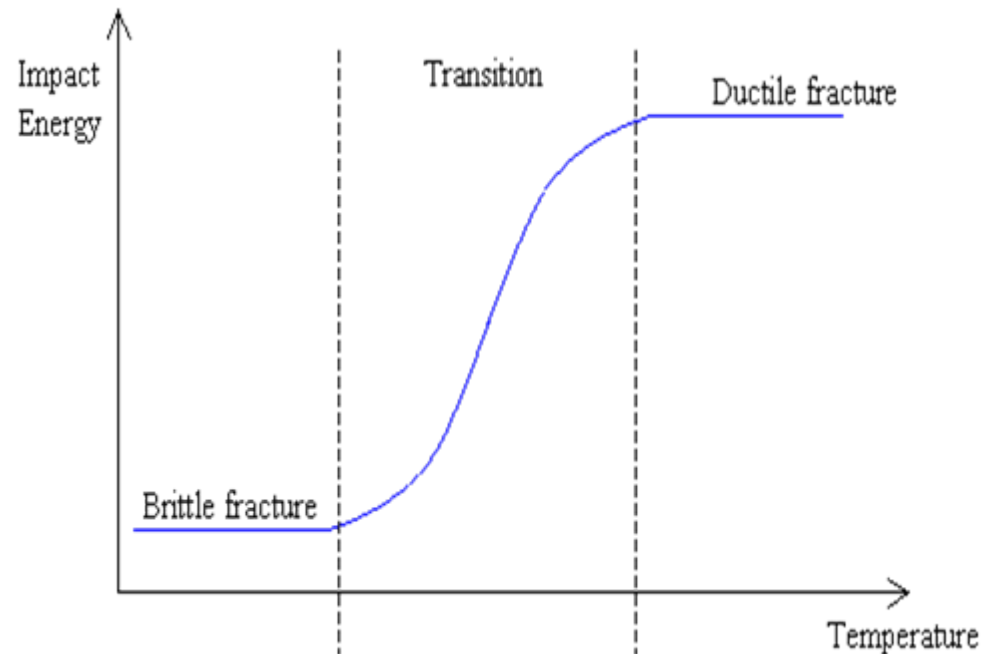


Purpose of this study

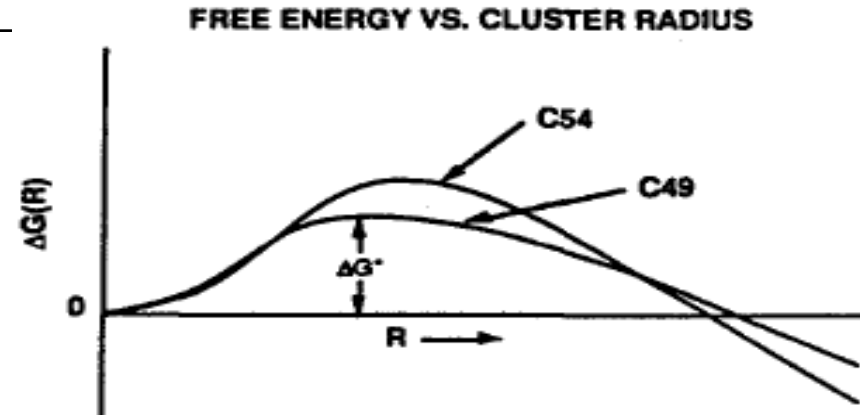
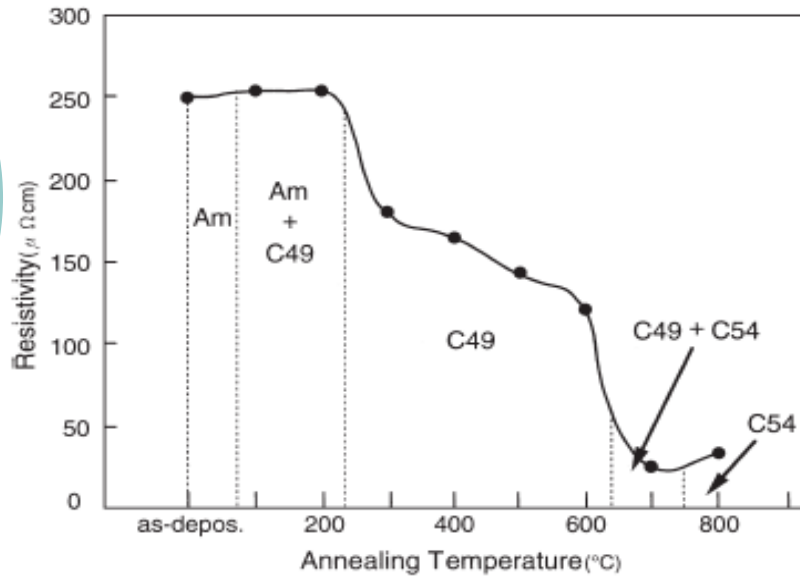
- Nanostructured material with grain sizes ($<100\text{nm}$)
- Grain size decreasing,
lowing temperature superplastic.
increasing ductility by Hall-Petch equation.
- Compared the difference of ductile brittle transition temperature (DBTT) for TiSi_2 bulk and thin film.

Ductile-Brittle Transition Temperature

- A sudden and dramatic drop in the energy absorbed by a metal subjected to impact loading.

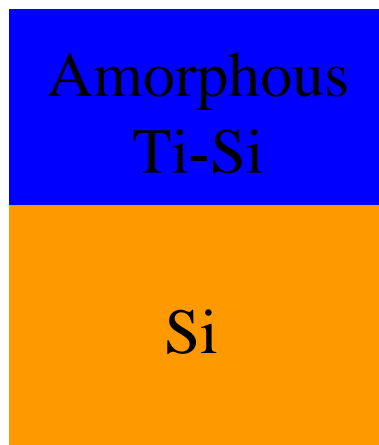


TiSi₂ films fabrication



K. Maex, Mater. Sci. & Eng. R., 11 (1993), pp. 53-153.

H. Inui, T. Hashimoto, K. Tanaka, T. Mizoguchi, H. Adachi, and M. Yamaguchi, Acta mater., 49 (2001), pp. 83-92.



co-sputtering

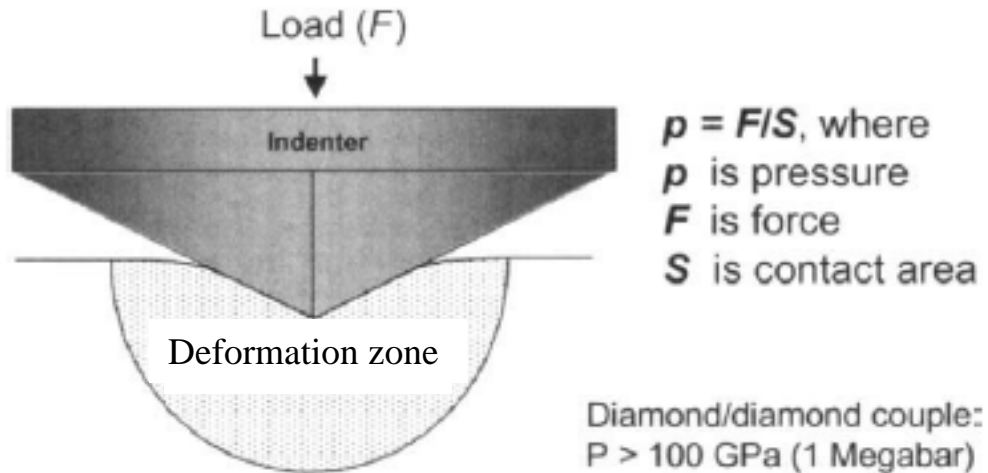


1st annealing



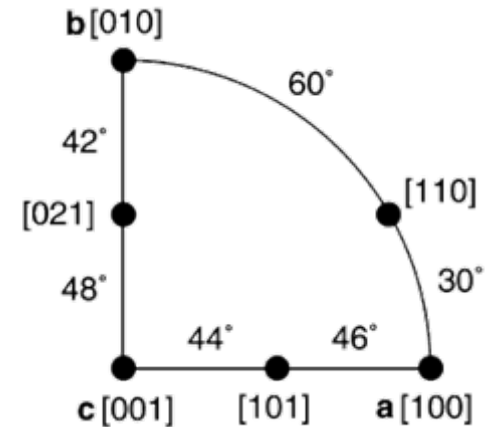
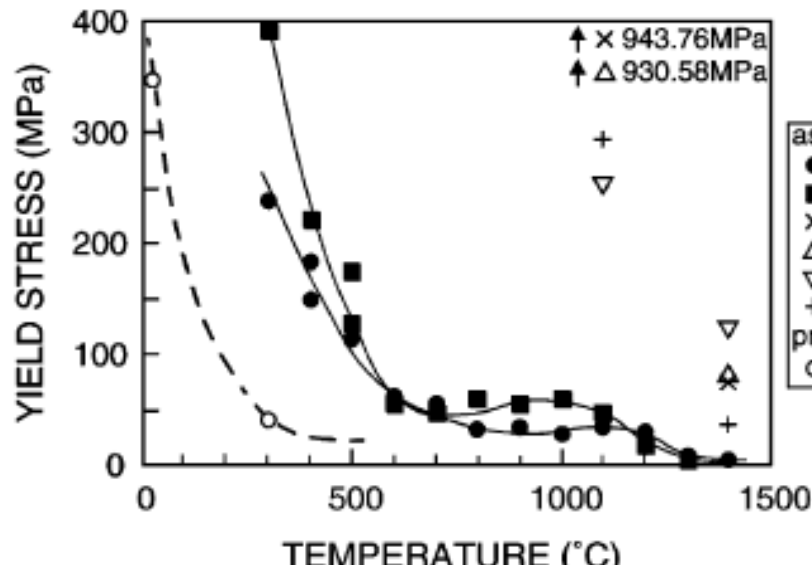
2nd annealing

Nanoindentation testing

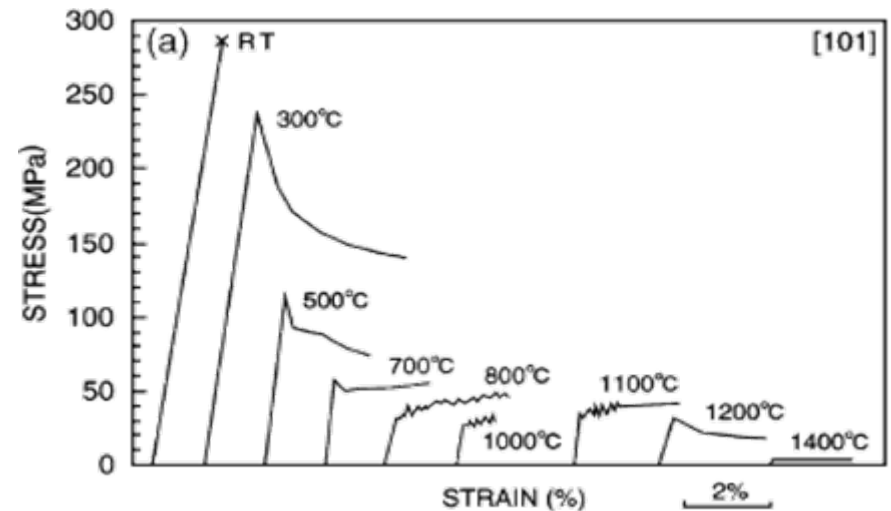


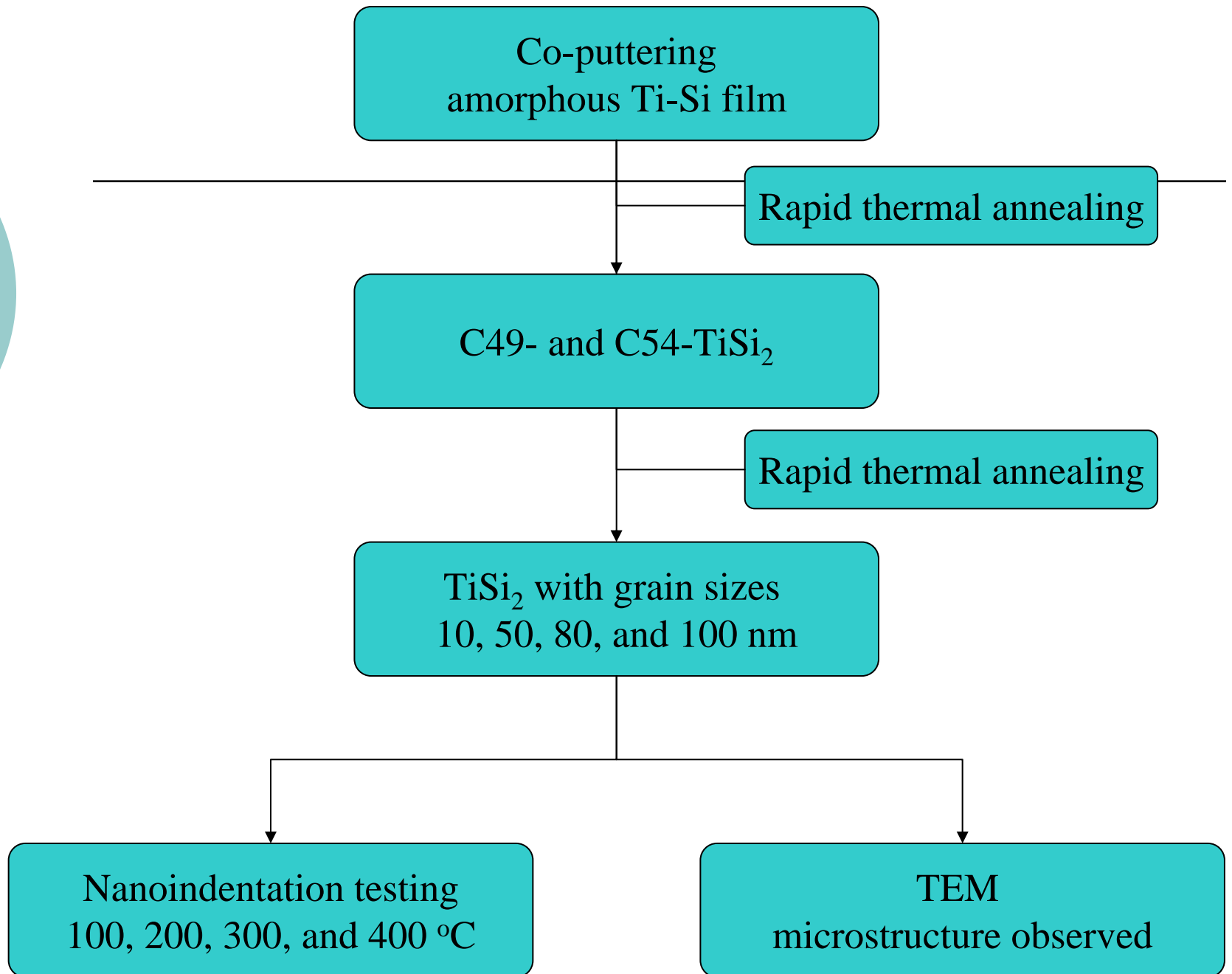
- **The C49- and C54-TiSi₂ examined with different temperatures and grain sizes.**
- Temperature range from 100 to 400°C
- The grains size range from 10 nm to 100 nm

TiSi₂ single crystal bulk

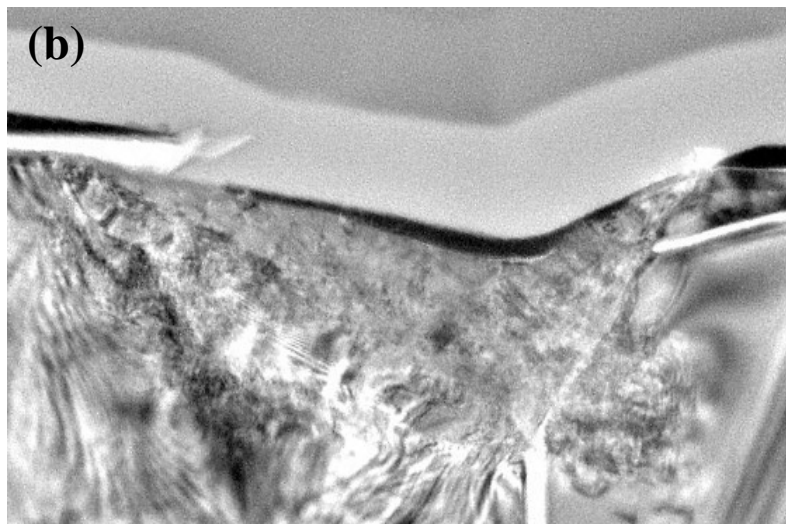
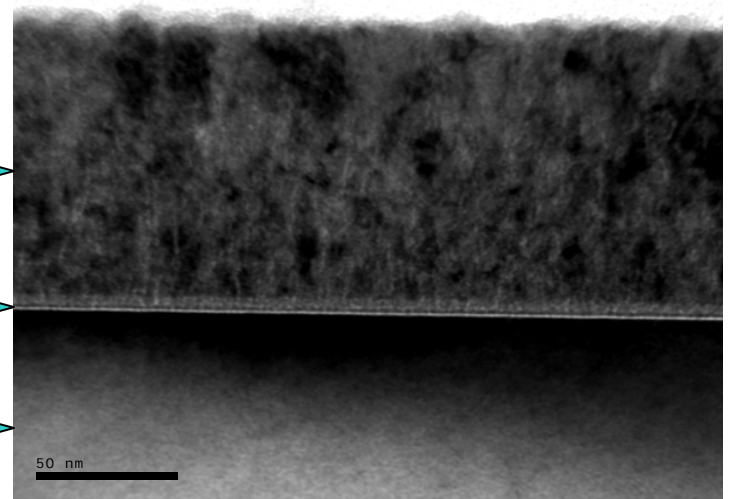
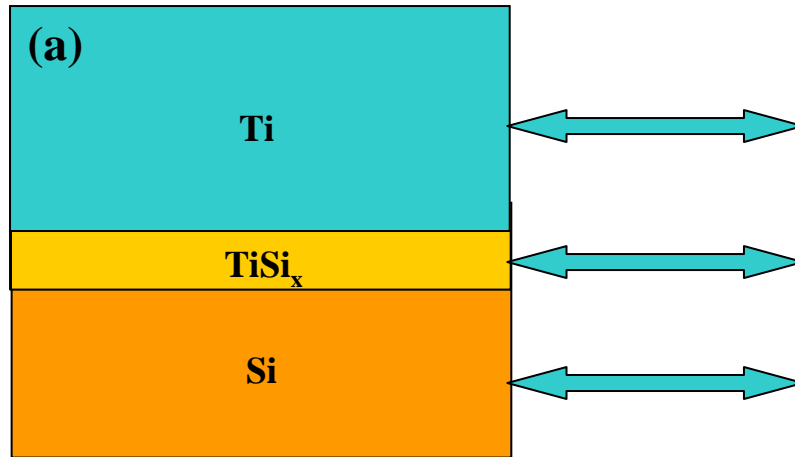


The TiSi₂ single crystal compressed with axes [001], [100], [010], [110], [101], and [021].





TiSi₂ nanocrystal thin film



(a) The Ti-Si films without deformation

(b) The Ti-Si films with deformation